

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Field device integration (FDI®) –  
Part 1: Overview**

**Intégration des appareils de terrain (FDI®) –  
Partie 1: Vue d'ensemble**



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INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

COMMISSION  
ELECTROTECHNIQUE  
INTERNATIONALE

ICS 25.040.40; 35.100.05

ISBN 978-2-8322-6441-6

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IEC 62769-1 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2021. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added references to Part 6-100 and Part 6-200 (technology mapping for .NET and HTML5);
- b) updated Subclause 8.3.1: major version, minor version and revision shall be written as two-digit numbers;
- c) added reference to new Part 8 and FDI® OPC UA Server Facet.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/854/CDV	65E/927/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/standardsdev/publications](http://www.iec.ch/standardsdev/publications).

A list of all parts in the IEC 62769 series, published under the general title *Field device integration (FDI)*<sup>®</sup>, can be found on the IEC website.

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# FIELD DEVICE INTEGRATION (FDI®) –

## Part 1: Overview

### 1 Scope

This part of IEC 62769 describes the concepts and overview of the Field Device Integration (FDI®<sup>1</sup>) specifications. The detailed motivation for the creation of this technology is also described (see 4.1). Reading this document is helpful to understand the other parts of this multi-part standard.

### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61804 (all parts), *Devices and integration in enterprise systems – Function Blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 61804-3, *Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) – Part 3: EDDL syntax and semantics*

IEC 61804-4, *Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) – Part 4: EDD interpretation*

IEC 62453 (all parts), *Field device tool (FDT) interface specification*

IEC 62541 (all parts), *OPC Unified Architecture*

IEC TR 62541-1, *OPC Unified Architecture – Part 1: Overview and concepts*

IEC 62541-3, *OPC Unified Architecture – Part 3: Address Space Model*

IEC 62541-4, *OPC Unified Architecture – Part 4: Services*

IEC 62541-5, *OPC Unified Architecture – Part 5: Information Model*

IEC 62541-100, *OPC Unified Architecture – Part 100: Device Interface*

IEC 62769-2, *Field Device Integration (FDI®) – Part 2: Client*

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